

upper side of said substrate adjacent the microstrip, said conductive ribbon connected to said waveguide wall and clamped between said head of said at least one screw and one of said plurality of ground surfaces.

5 13. (New) The transition of claim 10, further comprising:

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Concl*
a projection of said waveguide wall; and
at least one conductive elastic body being inserted between said projection and at least one of said first ground surface and said second ground surface.

14. (New) The transition of claim 11, further comprising:

a projection of said waveguide wall; and
at least one conductive elastic body being inserted between said projection and said at least one screw.

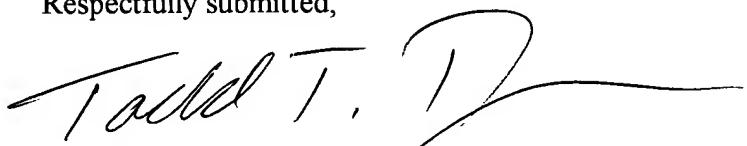
REMARKS

In compliance with MPEP § 608.01(q), Applicants submit that no new matter has been added in the substitute specification attached hereto. Applicants have included a marked-up copy of the original specification, the changes indicated therein corresponding to the changes implemented in the substitute specification.

In the event Applicants have overlooked the need for an extension of time, an additional extension of time, payment of fee, or additional payment of fee, Applicants hereby conditionally petition therefor and authorize that any charges be made to Deposit Account No. 20-0095, TAYLOR & AUST, P.C.

Should any question concerning any of the foregoing arise, the Examiner is invited to telephone the undersigned at (219) 897-3400.

Respectfully submitted,



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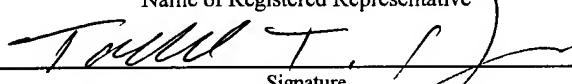
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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231, on: January 22, 2002.

Todd T. Taylor, Reg. No. 36,945
Name of Registered Representative


Signature

January 22, 2002
Date

Title: TRANSITION FROM A WAVEGUIDE TO A MICROSTRIP
Application Serial No.: Group: Examiner:

ATTACHMENT A:
MARKED-UP COPY SHOWING AMENDMENTS

IN THE SPECIFICATION

Attached herewith is a marked-up copy of the specification.

IN THE CLAIMS

Please cancel claims 1-7.

Please add the following new claims 8-14:

8. (New) A transition from a waveguide to a microstrip, comprising:

a substrate including a plurality of ground surfaces superimposed on one another, the microstrip extending on said substrate; and

a plurality of through-contacts providing electrical connectivity to said plurality of ground surfaces;

wherein the waveguide includes a waveguide wall with an opening therein, said substrate projecting through said opening into the waveguide such that at least a portion of the microstrip is disposed within the waveguide, at least one of said plurality of ground surfaces being in contact with said waveguide wall.

9. (New) The transition of claim 8, further comprising a through-plating in said substrate at an end of the microstrip, said through-plating disposed within the waveguide; wherein said end of the microstrip acts as an antenna.

10. (New) The transition of claim 8, wherein said plurality of ground surfaces include a first ground surface and a second ground surface, said first ground surface being superimposed on a surface of said substrate adjacent to a side of the microstrip and said second ground surface

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being superimposed on a surface of said substrate adjacent to an other side of the microstrip, said first and second ground surfaces being in contact with other of said plurality of ground surfaces via at least one of said plurality of through-contacts.

11. (New) The transition of claim 8, further comprising:

at least one screw; and
a support disposed proximate said waveguide wall, said substrate being fixedly connected to said support by said at least one screw;

wherein said at least one screw extends through said plurality of ground surfaces making electrical contact between said ground surfaces and said support.

12. (New) The transition of claim 11, further comprising a conductive ribbon, wherein said at least one screw lies with its head on one of said plurality of ground surfaces applied to an upper side of said substrate adjacent the microstrip, said conductive ribbon connected to said waveguide wall and clamped between said head of said at least one screw and one of said plurality of ground surfaces.

13. (New) The transition of claim 10, further comprising:
a projection of said waveguide wall; and
at least one conductive elastic body being inserted between said projection and at least one of said first ground surface and said second ground surface.

14. (New) The transition of claim 11, further comprising:
a projection of said waveguide wall; and
at least one conductive elastic body being inserted between said projection and said at least one screw.